4. Expansion Modules for Embedded Systems

Requirements for Embedded Systems
 VME Modules
 CompactPCI Modules
 Mezzanine Modules
 COM Express Modules

CompactPCI Modules

CompactPCI Modules
 CompactPCI Overview
 CompactPCI Express Modules
 CompactPCI PlusIO Modules
 CompactPCI Serial Modules

CompactPCI Overview (1)

CompactPCI, cPCI

CompactPCI®

- Industrial standard for modular computer systems
- Developed by the PCI Industrial Computer Manufacturers Group (PICMG)
- Aim: replacing the VME bus with the PCI bus
 - Combining the electrical specifications of the parallel PCI bus with the 3U and 6U Eurocard form factors

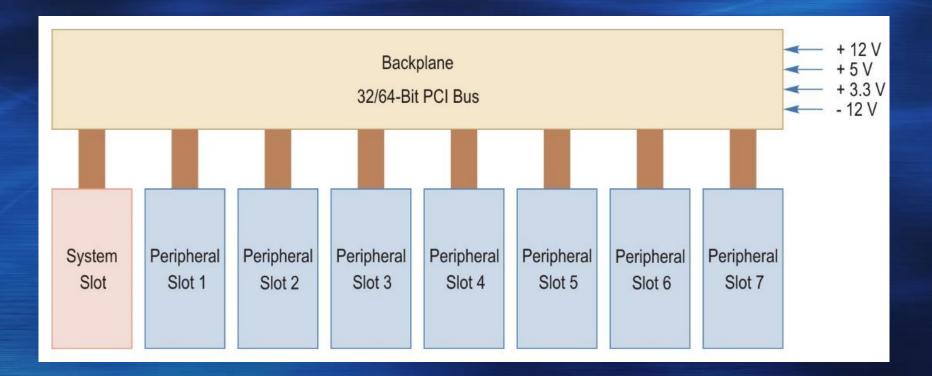
CompactPCI Overview (2)

Original CompactPCI modules: 32-bit or 64-bit parallel PCI bus

- Socket connectors
- 3U: J1 (32-bit bus), J2 (64-bit bus or userdefined I/O pins)
- 6U: J1, J2, and up to three optional connectors (J3, J4, J5) for I/O pins

 CompactPCI backplanes
 Plug (pin) connectors: P1, P2 (3U backplanes); P1...P5 (6U backplanes)

CompactPCI Overview (3)



CompactPCI Overview (4)

- Larger number of peripheral slots than in conventional PCI systems
 - High-quality pin-and-socket connectors
 - Large number of ground pins
- Connectors
 - HM (Hard Metric), step of 2 mm
 - 22 rows x 5 pins, keying area on J1
 - 6U module with 5 connectors: 535 pins

CompactPCI Overview (5)



3U CompactPCI module (© Extreme Engineering Solutions)

April 5, 2024

CompactPCI Overview (6)



6U CompactPCI chassis (© Kontron S&T AG)

April 5, 2024

CompactPCI Overview (7)

CompactPCI Extensions

Enable to use CompactPCI systems in various applications

Hot Swap (PICMG 2.1)

- Defines additional requirements for adding and removing modules during operation
- Pins of multiple lengths are provided
- Ethernet Connectivity (PICMG 2.16)
 - Enables to create a local area network between multiple expansion modules
 - Up to 2 Gbits/s for each CompactPCI slot

CompactPCI Overview (8)

CompactPCI Advantages

- Modularity, ruggedness
- Scalability
- Processor-independent
- Wide OS and software support, compatibility with existing drivers and applications
- Low cost of PCI and PCIe chips
- Extensions of the base specification enable to transition to serial interconnections

CompactPCI Modules

CompactPCI Modules
 CompactPCI Overview
 CompactPCI Express Modules
 CompactPCI PlusIO Modules
 CompactPCI Serial Modules

CompactPCI Express Modules (1)

PICMG EXP.0 extension

- The use of PCIe technology by CompactPCI backplanes
- Revision 2.0: support for Gen 2 and Gen 3 of the PCIe bus

CompactPCI Express system:

- System slot and board
- Peripheral slots and boards
- Switch slot and board
- Hybrid peripheral slots

CompactPCI Express Modules (2)

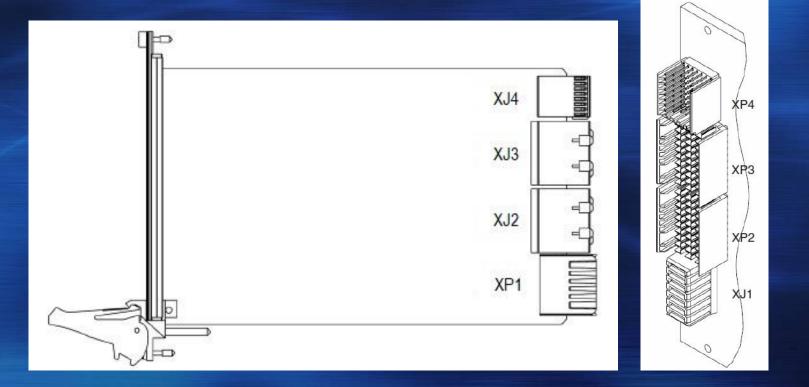
System slot and board Include up to 24 PCIe lanes, 2 or 4 PCIe links Peripheral slots and boards: Type 1, Type 2 Type 1 peripheral boards Same pin definitions as the system board Up to 16 PCIe lanes Type 2 peripheral boards Can be inserted into Type 1, Type 2, or hybrid peripheral slots Up to 8 PCIe lanes

CompactPCI Express Modules (3)

Connectors

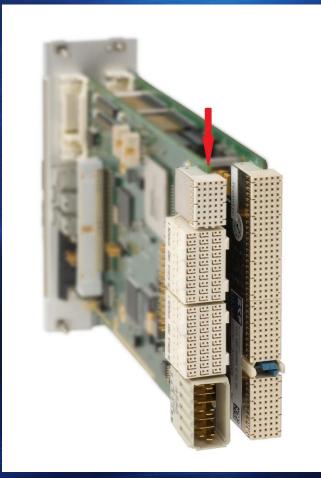
- J1/P1 and J2/P2 connectors replaced with improved connectors
- Connectors on system boards and Type 1 peripheral boards: XP1 (power); XJ2, XJ3 (differential signals); XJ4 (user I/O pins)
- Connectors on Type 2 peripheral boards: XJ3, XJ4
- The J3, J4, and J5 connectors on 6U boards are the same as in standard CompactPCI

CompactPCI Express Modules (4)



CompactPCI Express Modules (5)

XJ4/XP4 connector (top) eHM (enriched Hard Metric) ✓ XJ3/XP3, XJ2/XP2 connectors (middle) ADF (Advanced Differential) Fabric) XP1/XJ1 connector (bottom) UPM (Universal Power) Module) Power of 400 W



© EKF Elektronik GmbH

CompactPCI Modules

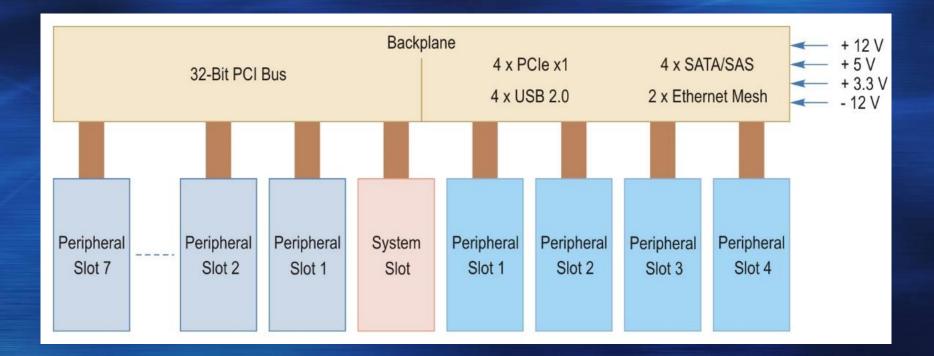
CompactPCI Modules
 CompactPCI Overview
 CompactPCI Express Modules
 CompactPCI PlusIO Modules
 CompactPCI Serial Modules

CompactPCI PlusIO Modules (1)

PICMG 2.30 extension

- Enables to add fast serial connections and serial interfaces in a standard way
- Specifies the pin assignment and function of user pins on the J2 connector
- Maintains the parallel PCI bus
 - Limited to 32 bits → J2 is used for serial interconnects
- Serial links/interfaces: 4 x PCIe (x1), 2 x Gigabit Ethernet, 4 x USB 2.0, 4 x SATA/SAS

CompactPCI PlusIO Modules (2)



CompactPCI PlusIO Modules (3)

- Full compatibility with 32-bit CompactPCI
 3U and 6U expansion modules
 - A system slot can control up to 7 CompactPCI and up to 4 CompactPCI PlusIO peripheral boards
 - Hybrid backplanes: include CompactPCI, CompactPCI PlusIO, and CompactPCI Serial slots
 - Hybrid systems enable to migrate to fully serial connections

CompactPCI Modules

CompactPCI Modules
 CompactPCI Overview
 CompactPCI Express Modules
 CompactPCI PlusIO Modules
 CompactPCI Serial Modules

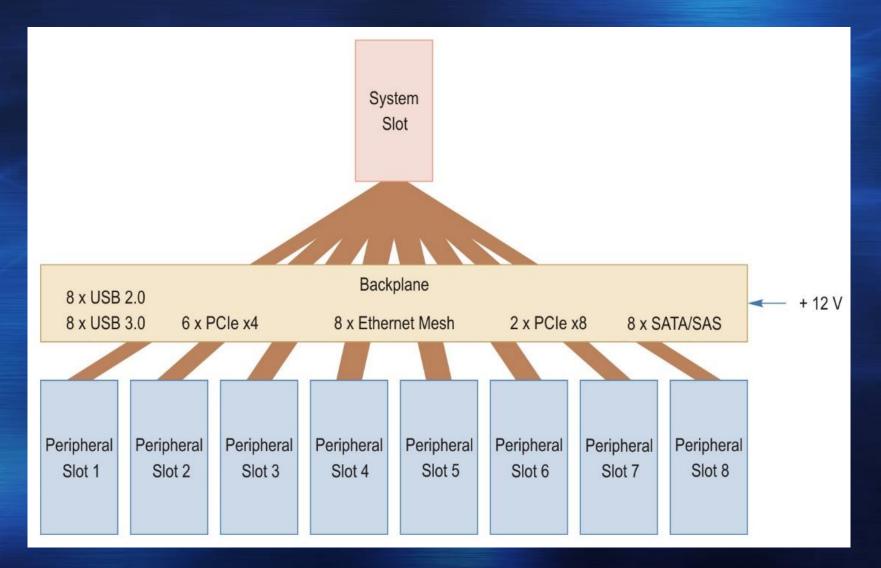
CompactPCI Serial Modules (1)

PICMG CPCI-S.0 extension

CompactPCI® Serial

- Completely replaces the parallel PCI bus with high-speed serial interconnects
- The original HM connectors are replaced with new connectors to support differential signaling
- 3U and 6U Eurocard form factors, with convection cooling or conduction cooling
- Supports hot swap of modules
- Fully passive backplane

CompactPCI Serial Modules (2)



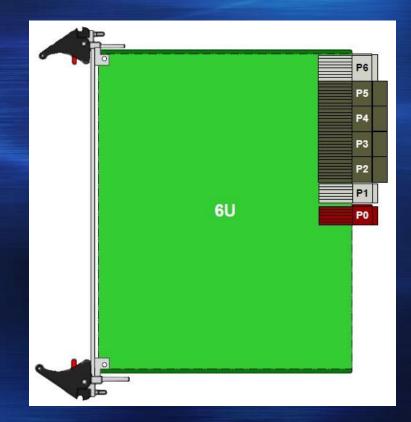
April 5, 2024

CompactPCI Serial Modules (3)

Interfaces supported by peripheral slots: One PCIe link (up to x8) One SATA/SAS interface One USB 2.0 interface One USB 3.0 interface Up to 8 Ethernet interfaces Connectors The plug connector is placed on the module AirMax connectors: support transfer rates of 12 Gbits/s; up to 184 pairs on a 3U module

CompactPCI Serial Modules (4)

- 3U modules: up to 6 connectors, P1 .. P6
- 6U modules: up to 7 connectors, P0 .. P6
- P2... P6: provide 360 user-defined I/O pins
- The pin assignment is identical for 3U and 6U modules
- P0 connector: provides additional Ethernet interfaces for servers



4. Expansion Modules for Embedded Systems

Requirements for Embedded Systems
 VME Modules
 CompactPCI Modules
 Mezzanine Modules
 COM Express Modules

Mezzanine Modules

Mezzanine Modules
 Overview of Mezzanine Modules
 Previous Mezzanine Modules
 Switched Mezzanine Card
 FPGA Mezzanine Card

Overview of Mezzanine Modules

Mezzanine modules: small cards designed to plug onto main (carrier) modules

- Placed in a plane parallel to the main module
- Provide flexibility to a main module
- Can extend the functions of the main module when there is not enough space
- Defined by industry standards
 - More cost-efficient than proprietary I/O modules
 - Carrier modules may use any architecture, e.g., VME, VXS, VPX, CompactPCI Serial

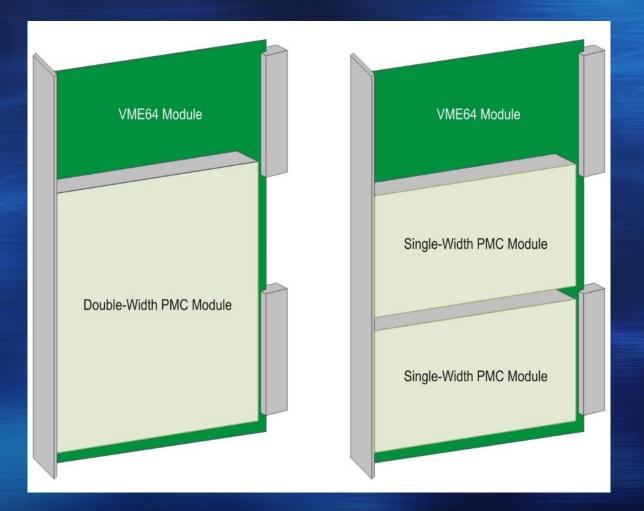
Mezzanine Modules

Mezzanine Modules Overview of Mezzanine Modules Previous Mezzanine Modules Switched Mezzanine Card FPGA Mezzanine Card

Previous Mezzanine Modules (1)

Common Mezzanine Card (CMC) IEEE 1386 standard Specifies a card and connector for VME bus PCI Mezzanine Card (PMC) Extension to the IEEE 1386 standard Combines the electrical features of the PCI bus with the mechanical features of CMC Single-width and double-width PMC modules Carrier modules: 3U or 6U Eurocard

Previous Mezzanine Modules (2)

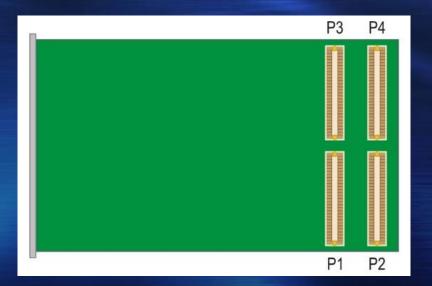


April 5, 2024

Previous Mezzanine Modules (3)

Mezzanine connectors on a PMC module

- P1, P2: for the 32-bit PCI bus
- P3: for the 64-bit PCI bus
- P4: for 64 user-defined I/O signals



Mezzanine Modules

Mezzanine Modules Overview of Mezzanine Modules Previous Mezzanine Modules Switched Mezzanine Card FPGA Mezzanine Card

Switched Mezzanine Card (1)

- XMC ANSI/VITA 42 standard
- Extends the PMC format with high-speed serial interconnects and new connectors
- ANSI/VITA standards
 - ANSI/VITA 42.0: Base specification
 - ANSI/VITA 42.2: Serial RapidIO protocol
 - ANSI/VITA 42.3: PCIe protocol

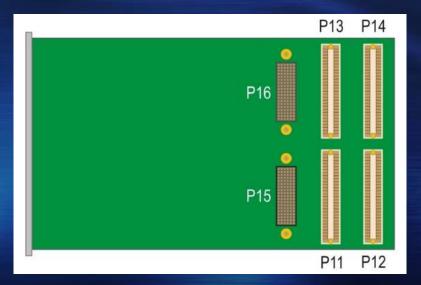
 ANSI/VITA 42.6: 10 Gigabit Ethernet protocol
 XMC modules are compatible with previous PMC modules

XMC

Switched Mezzanine Card (2)

Mezzanine connectors

1...4 connectors for the PCI bus: P11, P12, P13, P14 → same as P1, P2, P3, and P4
 1...2 high-density connectors for Gigabit serial interfaces: P15, P16



April 5, 2024

Switched Mezzanine Card (3)



XMC mezzanine module and CompactPCI Serial carrier module (© EKF Elektronik GmbH)

April 5, 2024

Mezzanine Modules

Mezzanine Modules Overview of Mezzanine Modules Previous Mezzanine Modules Switched Mezzanine Card FPGA Mezzanine Card

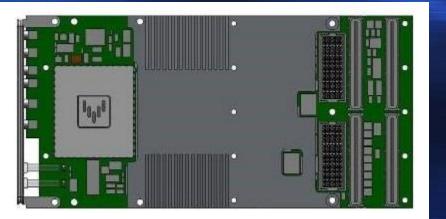
FPGA Mezzanine Card (1)

FMC – ANSI/VITA 57.1 standard

- Developed because PMC/XMC modules are not optimal for FPGA designs
- Specifies a mezzanine board, connectors, and modular interface to FPGA devices on a carrier board
- Carrier board: contains one or more FPGA devices; implements common functions
- FMC module: implements functions that can be variable within a system

FPGA Mezzanine Card (2)

- Single-width FMC module
 - 69 mm x 76.5 mm, one connector (P1)
- Double-width FMC module
 - 139 mm x 76.5 mm, 1 .. 2 connectors (P1, P2)





Single-width XMC module (left); Single-width FMC module (right)

FPGA Mezzanine Card (3)

- Low Pin Count (LPC) connector
 - 160 contacts
 - 68 single-ended or 34 differential signals
 - One full-duplex serial lane —> direct connection to a serial transceiver of an FPGA device
- High Pin Count (HPC) connector
 - 400 contacts
 - 160 single-ended or 80 differential signals
 - Output: Solution 20 differential pairs → connection to 10 serial transceivers
 - 4 differential clock signals, one I²C bus

FPGA Mezzanine Card (4)

FMC+ – ANSI/VITA 57.4 standard

- Improved connector: up to 24 multi-gigabit serial lanes, 28 Gbits/s per lane
- Defines triple-width FMC modules
- Enables to extend the length of the original FMC module by 10 mm → new connector with 8 serial lanes
- Aggregate data rate with the new connector: 32 x 28 Gbits/s = 896 Gbits/s

FPGA Mezzanine Card (5)

Connectors

- High Serial Pin Count (HSPC): 560 contacts (14x40)
- HSPC extension (HSPCe): 80 contacts (4x20)
- Mechanical design: SEARAY (Samtec, Inc.)



HSPC SEARAY connector (© Samtec, Inc.)

April 5, 2024

FPGA Mezzanine Card (6)



ADC/DAC FMC module (© VadaTech, Inc.)

April 5, 2024

4. Expansion Modules for Embedded Systems

Requirements for Embedded Systems
 VME Modules
 CompactPCI Modules
 Mezzanine Modules
 COM Express Modules

COM Express Modules

COM Express Modules
 COM Express Overview
 Type 10 COM Express Modules
 Type 6 COM Express Modules
 Type 7 COM Express Modules

COM Express Overview (1)

Computer on Module Express Family of modules of different sizes and pinout types A COM Express module may be used as: Single-board computer Processor mezzanine module connected to a carrier board Each COM Express module contains: Processor; memory; high-speed serial buses and interfaces

COI

COM Express Overview (2)

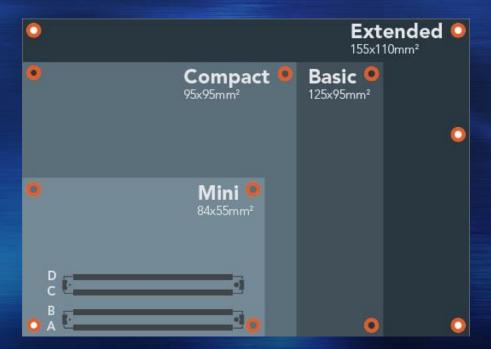
- Specification developed by the PICMG consortium
 - Current revision: 3.1 (2022)
 - Targeted for processors based on the x86 architecture (Intel, AMD)

Module sizes

- Mini (84 mm x 55 mm)
- Compact (95 mm x 95 mm)
- Basic (125 mm x 95 mm)
- Extended (155 mm x 110 mm)

COM Express Overview (3)

 Signals are routed to one or two highdensity connectors (step of 0.5 mm)
 A-B, C-D (220 pins each)



COM Express Overview (4)

Module Types

- Each type contains certain interfaces and has different pinout configuration
- Currently defined module types: 1, 10, 2, 3, 4, 5, 6, and 7
- Type 1, Type 10: a single connector
- Most commonly used: Type 10, Type 6
- Type 7: defined in Revision 3.0
- Power consumption: 68 W (one connector), 137 W (two connectors)

COM Express Overview (5)

Advantages of COM Express modules

- High performance: due to the high-speed serial buses and interfaces
- Flexibility: various module sizes and types
- Can be used standalone or with a usersupplied carrier board
- Reduced cost and development time
- Simple upgrades when used with a carrier board

COM Express Overview (6)

Applications

- Industrial control
- Railway transportation
- Data acquisition
- Medical equipment
- Military vehicles, aerospace modules
- Internet of Things (IoT)
- Type 7 modules: in data centers and for video surveillance

COM Express Modules

COM Express Modules
 COM Express Overview
 Type 10 COM Express Modules
 Type 6 COM Express Modules
 Type 7 COM Express Modules

Type 10 COM Express Modules (1)

Implemented in the Mini form factor Targeted to processors with low power consumption Limited number of interfaces PCIe bus with 1... 4 lanes Serial ATA (SATA) ports (1..2) Gb Ethernet port (1) Serial ports (0..2) \sim LPC (*Low Pin Count*) bus \rightarrow for connecting low-speed peripherals

Type 10 COM Express Modules (2)

- SPI (Serial Peripheral Interface) (1..2)
- System Management Bus (1)
- I²C bus (1)
- CAN (Controller Area Network) interface (optional)
- USB 2.0 ports (4 .. 8)

Optionally: 2 ports can be configured as USB 3.x

DDI (Digital Display Interface) (optional)

It can be adapted to: DVI, HDMI, DisplayPort, or SDVO (Serial Digital Video Out)

Type 10 COM Express Modules (3)

 LVDS (Low-Voltage Differential Signaling) channel (optional)

Embedded DisplayPort (eDP) on the LVDS pins (optional)



Type 10 COM Express module (© congatec GmbH)

April 5, 2024

COM Express Modules

COM Express Modules
 COM Express Overview
 Type 10 COM Express Modules
 Type 6 COM Express Modules
 Type 7 COM Express Modules

Type 6 COM Express Modules (1)

- Based on Type 2 modules
- Available in the Compact and Basic form factors
 - Targeted to processors with higher performance
- Two connectors
 - First connector: nearly the same pinout as that of Type 2 modules
 - Second connector: support for current and future serial interfaces

Type 6 COM Express Modules (2)

Interfaces

- Same as on Type 10 modules: Gb Ethernet, serial, LPC, SMBus, I²C, CAN, USB 2.0
- PCIe bus with 1 .. 24 lanes
- SATA ports (1 .. 4)
- 4 USB ports can be configured as USB 3.x
- Up to 3 DDI channels (optional)
- Up to 2 LVDS channels (optional)
- PCI Express Graphics (PEG) (optional): x16 PCIe connector

Type 6 COM Express Modules (3)



Type 6 Compact COM Express module (© congatec GmbH)

April 5, 2024

COM Express Modules

COM Express Modules
 COM Express Overview
 Type 10 COM Express Modules
 Type 6 COM Express Modules
 Type 7 COM Express Modules

Type 7 COM Express Modules (1)

Developed for modular server designs

- Available in the Basic and Extended form factors
 - Targeted to processors designed for servers

Interfaces removed:

4 USB 2.0, 2 SATA, all display interfaces

New buses/interfaces:

PCIe lanes (8)

10-Gb Ethernet (1...4): physical transmission layer not implemented on the module

Type 7 COM Express Modules (2)

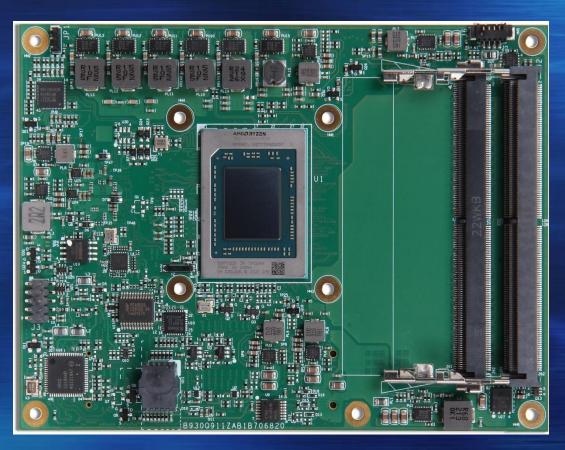
Reasons for removing SATA ports:

- Gradual replacement of hard disk drives by solid-state drives (SSDs)
- Replacement of SATA interface by the NVMe (Non-Volatile Memory Express) interface

Interfaces

- Same as on Type 6 modules: serial, LPC, SMBus, I²C, CAN, Gb Ethernet
- PCIe bus (up to x32), 2 SATA, 4 USB 2.0 (each configurable as USB 3.x), 10-Gb Ethernet

Type 7 COM Express Modules (3)



Type 7 Basic COM Express module (© American Portwell Technology, Inc.)

April 5, 2024

Summary (1)

- Requirements for embedded systems: high reliability, simple maintenance
 - Pin-and-socket connectors
 - Front panels and guiding systems
 - Passive backplanes
- Parallel VME modules
 - 3U, 6U, and 9U Eurocard form factors
 - P/J connector pairs
 - Standard, VME64x, and VME320 backplanes
 - Conduction-cooled modules are available

Summary (2)

VXS (VMEbus Switched Serial) modules

- Switch boards have point-to-point connections to payload boards
- Payload boards maintain compatibility with VME modules; contain an additional serial connector
- VXS backplane topologies: single star, dual star, mesh, daisy chain
- VPX modules
 - Use only serial interconnects
 - Connectors: MultiGig RT2 (Gen 4 VPX, 16 Gbits/s), MultiGig RT3 (Gen 5 VPX, 25.8 Gbits/s)

Summary (3)

- CompactPCI combines the parallel PCI bus with the 3U and 6U Eurocard form factors
 - Passive backplane
 - Larger number of peripheral slots
- CompactPCI Express modules and backplanes use the PCIe technology
 - System, peripheral, switch boards/slots
 - Improved connectors
- CompactPCI PlusIO maintains the 32-bit PCI bus and extends it with serial links/interfaces

Summary (4)

CompactPCI Serial replaces the parallel PCI bus with serial point-to-point interconnects

- Star topology
- PCIe links and various interfaces: SATA/SAS, USB, Ethernet
- Mezzanine modules are designed to plug onto main modules in a stacking configuration
- The Switched Mezzanine Card (XMC) is based on the previous PCI Mezzanine Card (PMC)
 - Extends the PMC format with serial interconnects and new mezzanine connectors

Summary (5)

- The FPGA Mezzanine Card (FMC) format has been developed for communication with FPGA devices located on a carrier board
 - The FMC+ format uses an improved connector and increases the number of serial lanes
- COM Express defines a family of module sizes and pinout types
 - Can be used for single-board computers
 - Module sizes: Mini, Compact, Basic, Extended
 - Commonly used pinout types: Type 10, Type 6, Type 7

Concepts, Knowledge (1)

- Features of the CompactPCI format
- Advantages of CompactPCI
- CompactPCI Express boards and slots
- CompactPCI PlusIO buses and interfaces
- CompactPCI Serial architecture
- CompactPCI Serial interfaces
- Advantages of mezzanine modules
- Features of the XMC format

Concepts, Knowledge (2)

- Features of the FMC format
- Improvements introduced by the FMC+ format
- COM Express module sizes and types
- Advantages of using COM Express modules
- Buses and interfaces included on Type 10 COM Express modules
- Differences between Type 6 and Type 10 COM Express modules